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(54) Title: PACKAGING MODULE AND PACKAGING METHOD THEREFOR, AND ELECTRONIC DEVICE

(54) 发明名称: 一种封装模组及其封装方法、电子设备

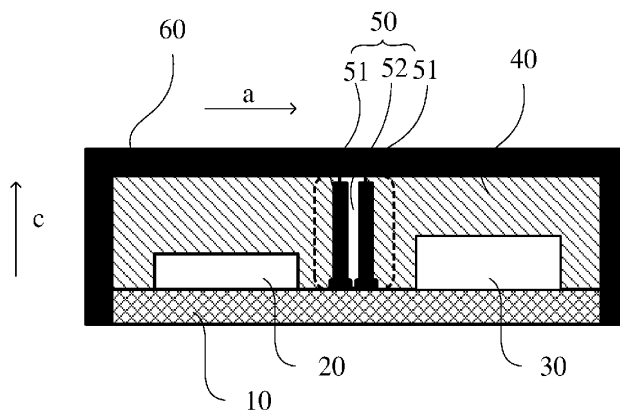


图 2a

(57) Abstract: Provided are a packaging module and a packaging method therefor, and an electronic device. The packaging module comprises at least two device groups, and a shielding structure for shielding the at least two device groups. The shielding structure comprises an isolation wall for electromagnetically isolating every adjacent two device groups. The isolation wall comprises a plurality of conductive pillars and a conductive adhesive, the conductivity of the conductive pillars being greater than that of the conductive adhesive. The plurality of conductive pillars are arranged at intervals and are electrically connected to a ground layer of a substrate. A gap between any adjacent conductive pillars is filled with the conductive adhesive, and any adjacent conductive pillars are electrically connected by means of the conductive adhesive. From the above description, it can be seen that the isolation wall is composed of the conductive pillars and the conductive adhesive, wherein the conductivity of the conductive pillars is greater than that of the conductive adhesive, thereby improving the conductivity of the isolation wall; and the conductive pillars are used as part of the isolation wall,

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which reduces the usage amount of the conductive adhesive, thereby reducing the cost of the whole shielding structure and as such reducing the cost of the whole packaging module.

(57) 摘要: 本申请提供了一种封装模组及其封装方法、电子设备, 封装模组包括至少两个器件组及用于屏蔽至少两个器件组的屏蔽结构。屏蔽结构包括用于电磁隔离每相邻的两个器件组的隔离墙。隔离墙包括多个导电柱及导电胶, 导电柱的导电率大于导电胶的导电率。多个导电柱间隔排列且与基板的地层电连接, 导电胶填充在任意相邻的导电柱之间的间隙内, 并通过导电胶将任意相邻的导电柱电连接。由上述描述可看出, 隔离墙采用导电柱与导电胶组成, 导电柱的导电率大于导电胶, 从而提升了隔离墙的导电率; 采用导电柱作为隔离墙的一部分, 减少了导电胶的使用量, 降低了整个屏蔽结构的成本, 进而降低整个封装模组的成本。